## **NIKAPLEX**

## 高耐熱ハロゲンフリーガラスエポキシ (FR-4.1)

Heat resistance and halogen-free glass epoxy (FR-4.1)

(アンクラッド積層板) L-6529

Unclad Laminates

ガラス布基材エポキシ樹脂積層板 (FR-4.1) Glass fabric base epoxy resin laminates (FR-4.1)

■特長 Characteristic

●パンチング加工性が良好です。 Punching workability is good. ●低発塵タイプです。 Dusting the amount has been r

Dusting the amount has been reduced.

●特性バランスが優れています。 Property balance is excellent.

■用途 Use applications

●印刷抵抗基板

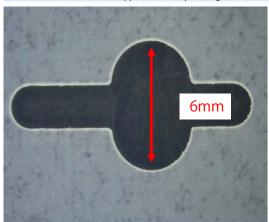
For printed resistor circuit

●各種絶縁板

For Various insulating plate



## ■パンチング加工後外観 Appearance after punching



■仕様 Specification ●アンクラッド積層板 Unclad laminates

| 日番       | 定尺寸法(縱×横)                 | 公称板厚及び板厚公差                                |             |             |
|----------|---------------------------|---|-------------|-------------|
| Products | Standard size ( Lw × Cw ) | Nominal thickness and Thickness tolerance |             |             |
| L-6529   | 1,020 × 1,020 mm          | 0.4±0.08 mm                               | 0.6±0.13 mm | 1.2±0.15 mm |

<sup>\*</sup>上記以外のサイズ、板厚及び板厚公差の仕様につきましては別途お問合せ下さい。

Please contact us separately concerning the size and the thickness and the thickness tolerance of the other than the above.

| ■一般特性例 Properties                              |                                 |                      |  |        |                              |  |  |  |  |
|--|---------------------------------|----------------------|--|--------|------------------------------|--|--|--|--|
| 試験 <sup>:</sup>                                | 処理条件<br>Treatment               | 単位<br>Unit           | 実測値<br>Actual value                      |        |                              |  |  |  |  |
| ガラス転移温度(Tg)<br>Glass transition temp           | TMA                             |                      | 昇温:10°C/min<br>Heating rate:10°C/min     | °C     | 125                          |  |  |  |  |
| 熱膨張係数  | X(横)                            | α1                   | TMA                                      | ppm/°C | 19                           |  |  |  |  |
| Coefficient of thermal expantion               | Y(縦)                            | α1                   | TIVIA                                    | ppm/°C | 17                           |  |  |  |  |
| 熱伝導率 Thermal conductivity                      | 比較定常法 Com                       | paring steady method | Α  | W/m •K | 0.5                          |  |  |  |  |
| はんだ耐熱性 260℃                                    | Solder heat resistance at 260°C |                      | Α  | 秒 sec. | ≧120                         |  |  |  |  |
| 反り Warpage                                     | リフロ一後                           | After reflow         | 社内法* <sup>1</sup><br>NIKKAN's own method | mm     | 0.5                          |  |  |  |  |
| 曲げ強さ Flexural strength                         | 縦 Lw /                          | ⁄横 Cw                | Α  | MPa    | 520 / 470                    |  |  |  |  |
| 曲げ弾性率 Flexural modulus                         | 縦 Lw /                          | ⁄横 Cw                | Α  | GPa    | 24 / 23                      |  |  |  |  |
| せん断強さ  | Α                               | MPa                  | 70                                       |        |                              |  |  |  |  |
| 体積抵抗率  | C-96/20/65                      | MΩ•m                 | 1 × 10 <sup>8</sup>                      |        |                              |  |  |  |  |
| 表面抵抗 Surface resistance                        |                                 |                      | C-96/20/65                               | МΩ     | 1 × 10 <sup>9</sup>          |  |  |  |  |
| 絶縁抵抗 Insulation resistance                     |                                 |                      | C-96/20/65                               | МΩ     | 1 × 10 <sup>9</sup>          |  |  |  |  |
| 粉落ち量   | Dust generation                 |                      | 社内法 <sup>*1</sup><br>NIKKAN's own method | mg/m   | 1.2                          |  |  |  |  |
| 比重 Specific gravity                            |                                 |                      | 1  | -      | 1.8                          |  |  |  |  |
| 吸水率 Water absorption                           |                                 |                      | E-24/50 + D-24/23                        | %      | 0.13                         |  |  |  |  |
| 表面粗さ Surface roughness Cw                      |                                 | Ra                   | μ m                                      | 0.3    |                              |  |  |  |  |
| 耐アルカリ性(3%NaOH溶液) Alkali resistance(3% NaoH aq) |                                 |                      | 40°C/3min 浸漬<br>Dip                      | _      | 異常なし<br>No remarkable change |  |  |  |  |
| 耐燃性 UL94 Flammability UL94                     |                                 |                      | E-24/125                                 | _      | 94V-0                        |  |  |  |  |

上記試験はJIS C 6481、JIS K6911に準じます。但し、熱伝導率は比較定常法に、反り、曲げ強さ及び粉落ち量は社内法に、 せん断強さはASTM D-732に、耐燃性はUL94に準じます。

- \*2 試験板厚は0.4mmです。
- \*3 上記は実測値であり、保証値ではございません。
- \*2 The sample thickness is 0.4mm.
- \*3 The abobe data is actual values and not guaranteed values.

<sup>\*1</sup> The above tests are in accordance with JIS C6481. However, thermal cinductivity is in accordance with comparing steady method, and warpage / flexural strength / dusting amount test is in accordance with NIKKAN's own method, shear strength is in accordance with ASTM D-732, and flame resistance is in accordance with UL94.